

AO3400

30V N-Channel Enhancement-Mode MOSFET

VDS= 30V

RDS(ON), Vgs@10V, Ids@5.8A < $28m\Omega$

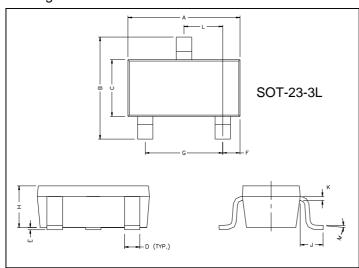
RDS(ON), Vgs@4.5V, Ids@5.0A < $33m\Omega$

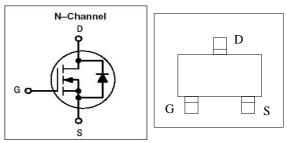
RDS(ON), Vgs@2.5V, Ids@4.0A < $52m\Omega$

Features

Advanced trench process technology
High Density Cell Design For Ultra Low On-Resistance

Package Dimensions





REF.	Millimeter		REF.	Millimeter		
	Min.	Max.	KEF.	Min.	Max.	
Α	2.70	3.10	G	1.90 REF.		
В	2.65	2.95	Н	1.00	1.30	
С	1.50	1.70	K	0.10	0.20	
D	0.35	0.50	J	0.40	-	
Е	0	0.10	L	0.85	1.15	
F	0.45	0.55	М	0°	10°	

Maximum Ratings and Thermal Characteristics (TA = 25oC unless otherwise noted)

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V_{DS}	30	V		
Gate-Source Voltage	V_{GS}	± 12			
Continuous Drain Current	Ι _D	5.8	A		
Pulsed Drain Current	I _{DM}	30			
Maximum Power Dissipation	$TA = 25^{\circ}C$	P _D	1.4	W	
waxmum Power Dissipation	TA = 75°C	ГD	1		
Operating Junction and Storage Temperature Range	T_J,T_stg	-55 to 150	°C		
Junction-to-Ambient Thermal Resistance (PCB mounted)	$R_{\theta JA}$	145	°C/W		

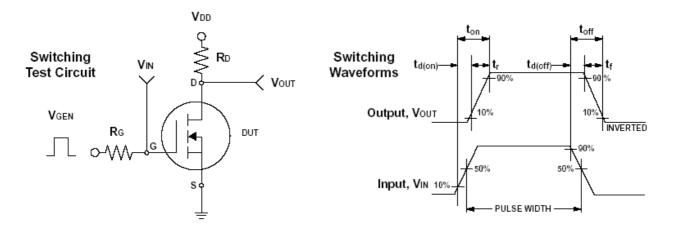


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ELECTRICAL CHARACTERISTICS (TA = 25oC unless otherwise noted)

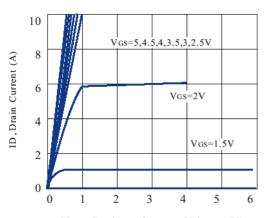
Parameter	Symbol	Test Condition	Min.	Тур.	Miax.	Unit
Static	•					
Drain-Source Breakdown Voltage	BV _{DSS}	$V_{GS} = 0V, I_D = 250uA$	30			V
Drain-Source On-State Resistance	R _{DS(on)}	$V_{GS} = 10V, I_D = 5.8A$		22.0	28.0	mΩ
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 4.5V, I _D =5A		27.0	33.0	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 2.5V, I _D =4A		43.0	52.0	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250uA$	0.7		1.4	V
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 24V$, $V_{GS} = 0V$			1	uA
Gate Body Leakage	I _{GSS}	$V_{GS} = \pm 12V, V_{DS} = 0V$			±100	nA
Forward Transconductance	G fs	$V_{DS} = 5V, I_{D} = 5A$	10	15	_	S
Gate Resistance	Rg	F=1.0MHz	6	7	7.5	Ω
Dynamic						
Total Gate Charge	Qg	$V_{DS} = 15V, I_D = 5.8A$ $V_{GS} = 4.5V$		11	14	nC ns
Gate-Source Charge	Q_{gs}			1.6		
Gate-Drain Charge	Q_{gd}			2.8		
Turn-On Delay Time	t _{d(on)}	V_{DD} = 15V, RL=2.7 Ω I_D = 1A, V_{GEN} = 10V R_G = 3 Ω		7	11	
Turn-On Rise Time	t _r			15	20	
Turn-Off Delay Time	t _{d(off)}			38	50	
Turn-Off Fall Time	t _f			3	10	
Input Capacitance	C _{iss}	101/1/		340		pF
Output Capacitance	C _{oss}	$V_{DS} = 10V, V_{GS} = 0V$ $f = 1.0 \text{ MHz}$		115		
Reverse Transfer Capacitance	C _{rss}	- = 1.U IVI⊓Z		33		
Source-Drain Diode	1	•	•	•	•	•
Max. Diode Forward Current	Is				1.6	А
Diode Forward Voltage	V_{SD}	I _S = 1.6A, V _{GS} = 0V			1.2	V

Note: Pulse test: pulse width <= 300us, duty cycle<= 2%





Characteristics Curve



VDS, Drain-to-Source Voltage (V)
Figure 1. Output Characteristics

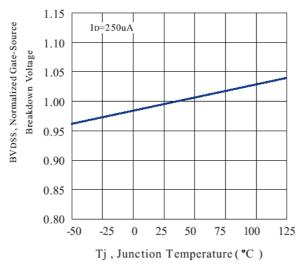


Figure 3. Breakdown Voltage Variation with Temperature

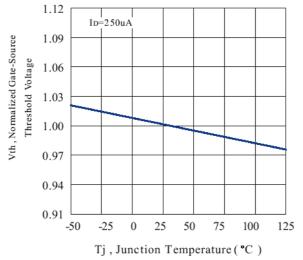


Figure 5. Gate Threshold Variation with Temperature

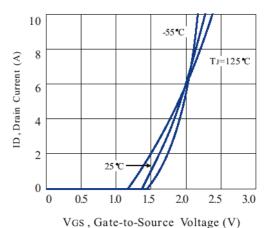


Figure 2. Transfer Characteristics

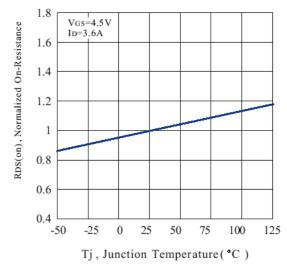
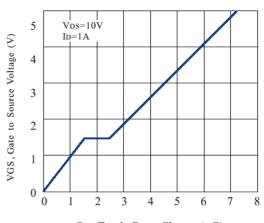


Figure 4. On-Resistance Variation with Temperatur



Qg, Total Gate Charge (nC) Figure 6. Gate Charge